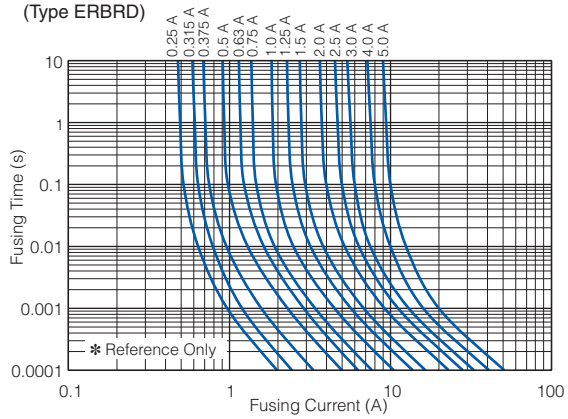
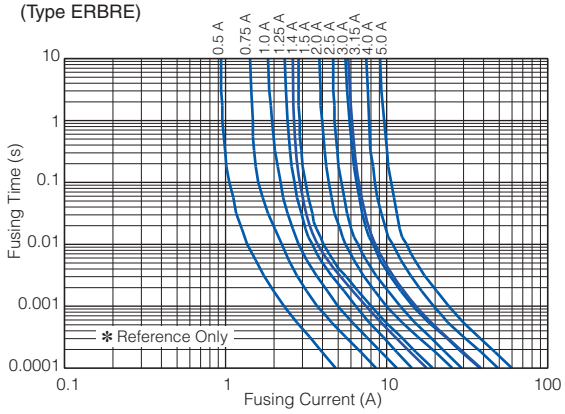
Fusing Characteristics (25 °C typical)

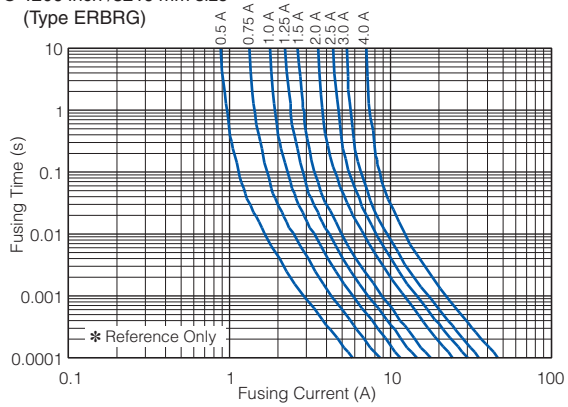
● 0402 inch / 1005 mm size
(Type ERBRD)



● 0603 inch / 1608 mm size
(Type ERBRE)



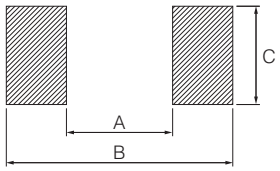
● 1206 inch /3216 mm size
(Type ERBRG)



Perfomance

Test Item	Performance Requirements	Test Conditions
Resistance	Within Specified Tolerance	25 °C
Resistance to Soldering Heat	±10 %	260 °C±5 °C, 10 s
Rapid Change of Temperature	±10 %	–40 °C (30 min.) / +125 °C (30 min.), 5 cycles
Damp Heat, Steady State	±10 %	60 °C, 90 % to 95 %RH, 1000 h (no load)
Load Life in Humidity	±10 %	60 °C, 90 % to 95 %RH, Load: 70 % rated current, 1000 h
Endurance at 70 °C	±10 %	70 °C , Load: 70 % rated current, 1000 h

Recommended Soldering Conditions



Part No. (inch size)	Dimensions (mm)		
	A	B	C
ERBRD(0402)	0.5 to 0.6	1.4 to 1.6	0.4 to 0.6
ERBRE(0603)	0.7 to 0.9	2.0 to 2.2	0.8 to 1.0
ERBRG(1206)	2.0 to 2.4	4.4 to 5.0	1.2 to 1.8

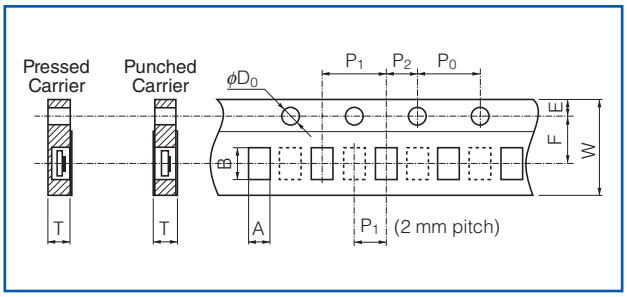
Design and specifications are each subject to change without notice. Ask factory for the current technical specifications before purchase and/or use.
Should a safety concern arise regarding this product, please be sure to contact us immediately.

Packaging Methods

● Standard Quantity

Part No.	inch size	Kind of Taping	Pitch (P_1)	Quantity
ERBRD	0402	Pressed Carrier Taping	2 mm	10,000 pcs./ reel
ERBRE	0603	Punched Carrier Taping	4 mm	5,000 pcs./ reel
ERBRG	1206			

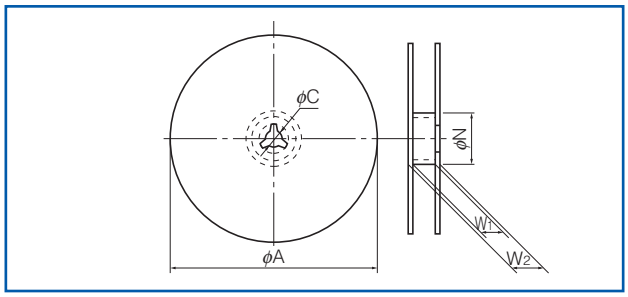
● Carrier Taping (Unit : mm)



Part No.	A	B	W	F	E
ERBRD	$0.68^{\pm0.10}$	$1.20^{\pm0.10}$	$8.00^{\pm0.20}$	$3.50^{\pm0.05}$	$1.75^{\pm0.10}$
ERBRE	$1.10^{\pm0.10}$	$1.90^{\pm0.10}$			
ERBRG	$2.00^{\pm0.15}$	$3.60^{\pm0.20}$			

Part No.	P_1	P_2	P_0	ϕD_0	T
ERBRD	$2.00^{\pm0.10}$	$2.00^{\pm0.05}$	$4.00^{\pm0.10}$	$1.50^{+0.10}_{0}$	$0.67^{\pm0.07}$
ERBRE	$4.00^{\pm0.10}$				$0.78^{\pm0.07}$
ERBRG					$0.84^{\pm0.07}$

● Taping Reel (Unit : mm)



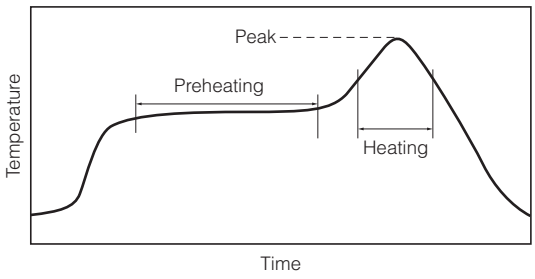
Part No.	φA	φN	φC	W_1	W_2
ERBRD ERBRE ERBRG	$180.0^{0}_{-1.5}$	$60^{+1.0}_{0}$	$13.0^{\pm0.2}$	$9.0^{+1.0}_{0}$	$11.4^{\pm1.0}$

Recommended Soldering Conditions

Recommendations and precautions are described below.

● Recommended soldering conditions for reflow

- Reflow soldering shall be performed a maximum of two times.
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



For soldering (Example : Sn/Pb)

	Temperature	Time
Preheating	140 °C to 160 °C	60 s to 120 s
Main heating	Above 200 °C	30 s to 40 s
Peak	235 ± 5 °C	max. 10 s

For lead-free soldering (Example : Sn/Ag/Cu)

	Temperature	Time
Preheating	150 °C to 180 °C	60 s to 120 s
Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s

● Recommended soldering conditions for flow

	For soldering		For lead-free soldering	
	Temperature	Time	Temperature	Time
Preheating	140 °C to 180 °C	60 s to 120 s	150 °C to 180 °C	60 s to 120 s
Soldering	245 ± 5 °C	20 s to 30 s	max. 260 °C	max. 10 s

<Repair with hand soldering>

- Preheat with a blast of hot air or similar method. Use a soldering iron with a tip temperature of 350 °C or less. Solder each electrode for 3 seconds or less.
- Never touch this product with the tip of a soldering iron.

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Should a safety concern arise regarding this product, please be sure to contact us immediately.